MONOLITHIC CERAMIC CAPACITORS CERAMIC CHIP CAPACITORS COG AND TEMPERATURE COMPENSATING TYPES

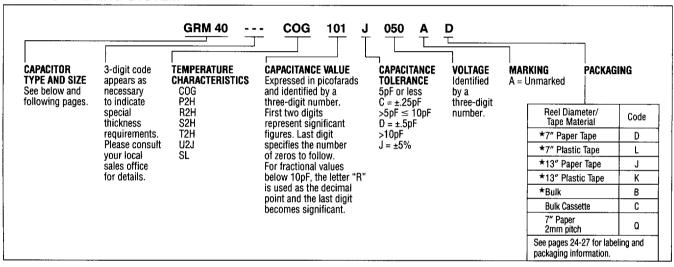


FEATURES

- Miniature size
- No Polarity
- Nickel Barrier Termination Standard highly resistant to metal migration
- Uniform dimensions and configuration
- Flow for GRM39, 40, 42-6 and Reflow Solderable
- Minimum series inductance
- Tape and Reel Packaging
- Wide selection of capacitance values and voltages
- Largest production capacity and volume in the world



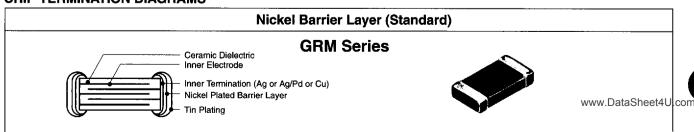
PART NUMBERING SYSTEM



CHIP DIMENSIONS

Dimensions: mm	Size	EIA Code	L Length	W Width	T Thickness	g (min.) Insulation	e (min.) Termination
	GRM 36	0402	1.0 ± 0.05	0.5 ± 0.05	0.5 ± 0.05	0.3	0.1
	GRM 39	0603	1.6 ± 0.1	0.80 ± 0.1	0.8 ± 0.1	0.5	0.35 ± 0.15
	GRM 40	0805	2.0 ± 0.15	1.25 ± 0.15	1.25 max.	0.75	0.5 ± 0.25
	GRM 42-6	1206	3.2 ± 0.15	1.6 ± 0.15	1.25 max.	1.0	0.55 ± 0.25
	GRM 42-2	1210	3.2 ± 0.15	2.5 ± 0.15	1.5 max.	1.0	0.5 ± 0.25
	GRM 43-2	1812	4.6 ± 0.3	3.2 ± 0.2	2.75 max.	2.0	0.63 ± 0.38
	GRM 44-1	2220	5.6 ± 0.3	5.1 + 0.25 - 0.5	2.75 max.	2.0	0.63 ± 0.38

CHIP TERMINATION DIAGRAMS



ALL PRODUCTS ON THIS PAGE ARE AVAILABLE AS STANDARD THROUGH AUTHORIZED MURATA ELECTRONICS DISTRIBUTORS.

MONOLITHIC CERAMIC CAPACITORS SPECIFICATIONS—COG AND TEMPERATURE COMPENSATING TYPES



GRM Series

GENERAL

Temperature Coefficient	Temperature Range	
$COG = 0 \pm 30 \text{ ppm}^*$	−55° to +125°C	
$P2H = N150 \pm 60 ppm$	−55° to +85°C	
$R2H = N220 \pm 60 ppm$	−55° to +85°C	
$S2H = N330 \pm 60 ppm$	−55° to +85°C	
$T2H = N470 \pm 60 ppm$	−55° to +85°C	
$U2J = N750 \pm 120 ppm$	-55° to +85°C	
SL = N1000 to P350	−55° to +85°C	

Refer to EIA-RS198D for other limitations

ELECTRICAL

TEST			
Capacitance & Q (Frequency & Voltage):	≤1000pF 1MHz ± 100Hz @ 1.0 ± .2 Vrms >1000pF 1KHz ± 100Hz @ 1.0 ± .2 Vrms		
Q Limits	≤30pF: 400 + (20xC (pF)) >30pF: 1000 minimum		
Insulation Resistance (I.R.)	100,000 megohms or 1000 megohms – mfd (whichever is less) with rated voltage applied for 2 minutes max with 50mA limiting current		
Dielectric Strength (Flash)	250% of rated voltage for 5 seconds with series resistor limiting charging current to 50mA max.		
Aging	Negligible		

MECHANICAL

TEST	TEST METHOD	POST TEST LIMITS	
Termina! Adhesion	Glass Epoxy Board	≤0603 1.0 lbs. ≥0805 2.2 lbs. No evidence of termination peeling	
Deflection	Capacitor R340 - Deflection Unit: mm - 45 - 45 - Supporter Supporter	2 mm deflection (paper phenol board) 1 mm deflection (Glass epoxy board) No mechanical damage Cap., DF, IR meet initial limits	
Solderability	MIL-STD-202 Method 208F	Contact factory for test limits	

ENVIRONMENTAL

TEST	TEST M	ETHOD	POST TEST LIMITS Appearance: No visual damage $\Delta C: = \pm 2.0\% \text{ or } \pm 0.5 \text{pF (whichever is greater)}$ $\Omega: >30 \text{pF} = 1,000 \text{ min.,} \le 30 \text{pF} = 400 + [20 \times \text{C(pF)}]$ I.R.: = 100,000MΩ min. or 1,000MΩ•μF (whichever is less)	
Thermal Shock (Air to Air)	MIL-STD-202, Method 107, Con Post thermal Shock measurements stabilization.	dition A ent shall be taken after 24 hours		
	RATED VOLTAGE	LOW VOLTAGE	Annagana Na dafaata	
Humidity	Apply rated voltage for 500 ± 12 hours at 85°C and 85% relative humidity	Apply .5 Vrms for 250 ± 12 hours at 85°C and 85% relative humidity	Appearance: No defects Capacitance: $\pm 3\%$ or $\pm .3$ pF (whichever is less) Ω: >30 pF = 500 min., ≤ 30 pF = $200 + [10 \times C(pF)]$ I.R.: $10,000$ M Ω or 100 M Ω -mfd. (whichever is less)	
	See Note 1	See Note 1	Flash: 250% rated voltage	
Life Test	Apply 200% of rated voltage fo maximum operating temperature		Appearance: No defects Capacitance: $\pm 3\%$ or $\pm .3$ pF (whichever is greater) Q: >30 pF = 500 min., ≤ 30 pF = $200 + [10 \times C(pF)]$ 1.R.: $10,000$ M Ω or 100 M Ω -mfd. (whichever is less) Flash: 250% rated voltage	

Note 1: Upon completion of either above test wait 24 hours prior to performing post testing.

Note 2: Upon completion of above test wait 24 hours prior to performing post testing.

STORAGE LIFE

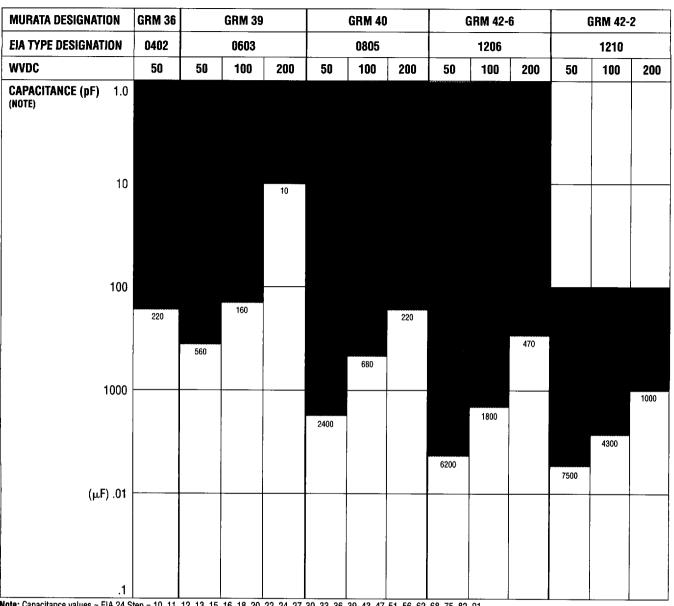
Chip component terminations should generally be protected from moisture. In addition, they should also be protected from materials containing chlorine, sulfur compounds or any harmful gases that could cause degradation of the solder.

- 1. All chip components, including tape and reel, should be kept in an area where the temperature is less than 40°C and where the humidity is less than 70%.
- 2. The chip components should be used within six months.
- 3. The solderability of the chip components should be rechecked in the event that they are not used in six months.
- 4. Peel strength and shelf life of tape are guaranteed for 1 year when stored under afore said conditions.

MONOLITHIC CERAMIC CAPACITORS CERAMIC CHIP CAPACITORS COG TYPE



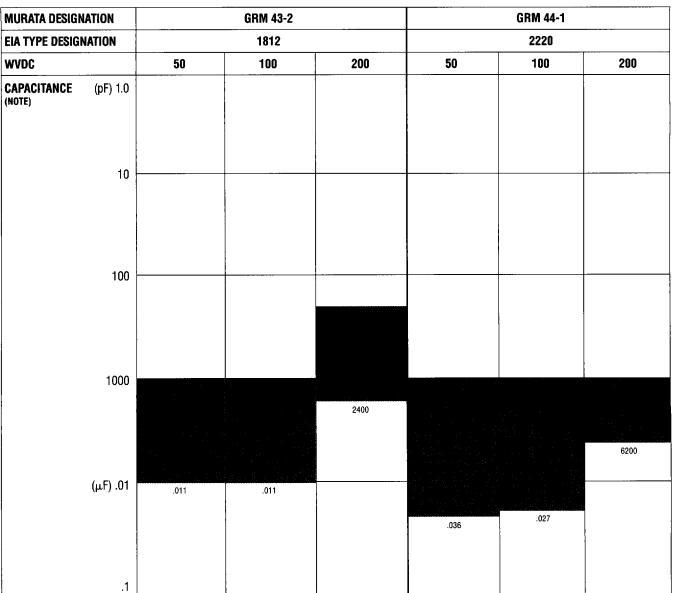
GRM Series



MONOLITHIC CERAMIC CAPACITORS CERAMIC CHIP CAPACITORS COG TYPE

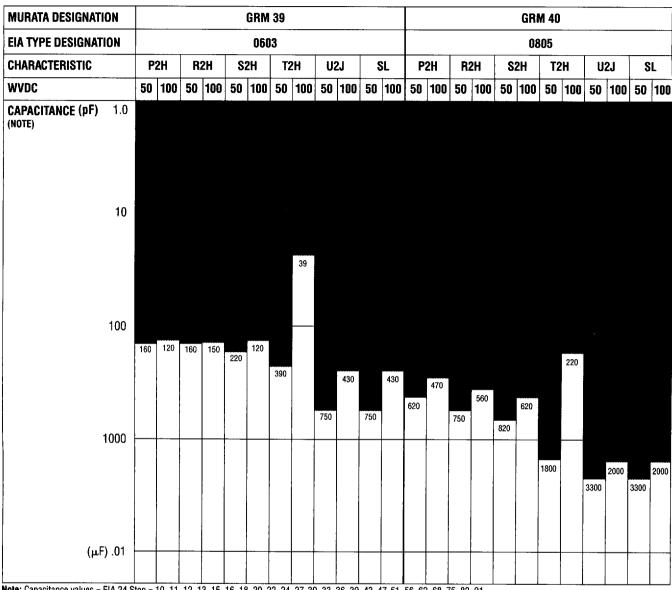


GRM Series



MONOLITHIC CERAMIC CAPACITORS CERAMIC CHIP CAPACITORS TEMPERATURE COMPENSATING TYPE





MONOLITHIC CERAMIC CAPACITORS CERAMIC CHIP CAPACITORS TEMPERATURE COMPENSATING TYPE



